

SDF100-1AB Epoxy Resin HT

Technical datasheet



Description & Application

SDF100-1AB is a high temperature curing two-component epoxy resin system. It is easier to use these two components. Thixotropy and adaptive characteristics. It is mainly used for the Filament winding, RTM and vacuum infusion technology to make the carbon fiber composites. High temperature resistance of 150 degrees Celsius for a long time.

Product data

	Epoxy resin 100-1A	Harder 100-1B	Mixed Adhesive
Appearance	Transparent	Yellowish	
Specific gravity	1.05-1.15	1.05	
Viscosity at 25°C (Pa.s)	1500-2000	100	
Mixing Ratio (weight)	100	80	
Pot life at 25°C (100gr)			3 days
Curing Conditions			1h at 130°C or 30min at 150°C

Processing

1. Adhesive products need to be kept dry and clean; the workplace needs to be ventilated;
2. Please check Agent A before use, observe whether there is sedimentation, and stir Agent A well;
3. The amount is taken according to the proportion and the weighing is accurate. Please remember that the proportion is the weight ratio rather than the volume ratio. After the A and B agents are mixed, they must be stirred well to avoid incomplete curing;
4. First heat the resin to 40 °C (in winter)
5. Weigh accurately according to the ratio, stir evenly and stand still without bubbles.
6. Add the mixed liquid to the glue tank, keep the glue tank temperature above 20 °C for extrusion.
7. Very few people will have mild skin allergies and mild itching during prolonged contact with glue. It is recommended to wear protective gloves when using it. Please wipe it off with acetone or alcohol and clean it with a detergent;
8. Before using it in large quantities, please try it in a small amount to master the use skills of the product to avoid mistakes.

Typical cured properties

Impact strength	KJ/m	1.68
Fracture toughness	N/m	141
Modulus of elasticity	3600MPa HDT	95 °C
Compressive strength	Kg/mm ²	32
Bending strength	Kg/mm ²	16
Tensile strength	Kg/mm ²	21
Impact strength	Kg/mm ²	12
Dielectric constant	1KHZ	3.6
Hardness	Shore D	88
Tg temperature	°C	150
Heat resistance temperature	°C	300 (3-5min)
Heat resistance temperature	°C	400 (1min)
Withstand voltage	Kv/mm	22

The above performance data are typical data measured in a laboratory environment with a temperature of 25 °C and a humidity of 70%, and are for customer reference only.